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### CDFP PCIe Generation 6 Connector System >

The next-generation CDFP PCIe Generation 6 external cable system delivers high-speed data transmission rates up to 64Gbps PAM-4 and meets the PCI Express (PCIe) Generation 6 standard, enabling data centers to upgrade and meet the needs of data-intensive applications such as AI inter-rack; Compute Express Link (CXL); network interface cards (NICs); and just-abunch-of-disks (JBOD) and just-a-bunch-of-flash (JBOF) storage devices.



#### Enables high-speed data transmission rates up to 64Gbps PAM-4, 256Gbps per 16x connector

The design meets PCIe Generation 6 standards with 85-Ohm impedance and is upgradable to PCIe Generation 7 standards.

#### **Facilitates design flexibility**

The connector system is backward compatible with previous zCD generations; supports belly-to-belly configurations; offers various cable lengths up to 2.0m; and supports 4x, 8x and 16x configurations, including cable bifurcation.

Data Rates	Up to 64Gbps PAM-4, 256Gbps per 16x connector
Data Transmission Standard	PCIe Generation 6 (upgradable to PCIe Generation 7)
Form Factor	SFF-TA-1032
Circuits	120 positions (16x connector)
Cable Lengths	0.5 to 2.0m
Operating Temperatures	-40 to +85°C

### Reduces space requirements with high-density applications

With 16 lanes in a compact form factor, the connector meets SFF-TA-1032 standards.

#### **Delivers enhanced signal integrity**

The improved cage design uses electromagnetic interference (EMI) spring fingers to help prevent signal degradation.

#### **MARKETS AND APPLICATIONS**

#### Server and Storage

Al clusters CXL 2.0/3.0 switching and memory systems PCIe solid state drive (SSD) storage devices High-performance computing systems JBOD storage arrays JBOF storage arrays

#### Networking

Enterprise computing systems Top-of-rack switches Disaggregated NICs

#### Telecommunications

Core switches Routers







AI Clusters

Enterprise Computing Systems

Core Switches

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#### **PRELIMINARY SPECIFICATIONS**

#### **Reference Information**

Packaging: Tray Designed in: Millimeters RoHS: Yes Halogen Free: Yes Glow Wire Capable: Yes Form Factor Standard: SFF-TA-1032 Mates With: zCD connector, CDFP PCle Gen 6 connector

#### **Electrical**

Voltage (max.): 30V RMS/DC Current (max.): 1.0A Contact Resistance: 10 milliohms Dielectric Withstanding Voltage: 300V DC Insulation Resistance: 100 Megohms

#### Mechanical

Cage Height: 12.98mm Cage Width: 36.74mm Cable Length: 0.5 to 2.0m Attachment: Surface-mount technology Circuit Size: 120 positions (16x connector) Durability (max.): 250 cycles

#### Physical

Wafer Housing: High-temperature thermoplastic, glass-filled UL 94V-0 Diecast Housing: Nickel-plated zinc alloy EMI Fingers: Nickel-plated copper alloy Cable: 29 AWG (data) and 31 AWG (side band) Contact Plating: Gold Underplating: Nickel PCB Thickness: 1.35mm Operating Temperatures: -40 to +85°C

#### www.molex.com